



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PLCC2 SMD
- ▶ 2835 1W Series
- ▶ Yellow (590nm)

NOY15S54



Release Date: 26 November 2014 Version: A1.0



2835 1W Series



FEATURES:

- **Package:** PLCC2 High Power White SMT Package
- **Forward Current:** 350mA
- **Forward Voltage (typ.):** 2.4V
- **Luminous Flux (typ.):** 36m @350mA
- **Colour:** Yellow
- **Wavelength:** 590nm
- **Viewing angle:** 120°
- **Materials:**
 - Die: AlGaInP
 - Resin: Silicon (Water Clear)
 - L/T Finish: Ag plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous flux
 - Dominant wavelength
- **Soldering methods:** IR Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with 2000/reel, ø180mm (7'')

APPLICATIONS:

- Decorative Lighting
- Backlighting
- Indicator
- Display

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	350	mA
Peak Forward Current (Duty 1/10; width 10KHz)	I_{FP}	700	mA
Reverse Current @5V	I_R	10	μ A
Power Dissipation	P_D	1050	mW
Electrostatic Discharge	ESD	2000	V
Junction Temperature	T_j	115	°C
Operating Temperature	T_{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+100	°C
Soldering Temperature	T_{SD}	260	°C

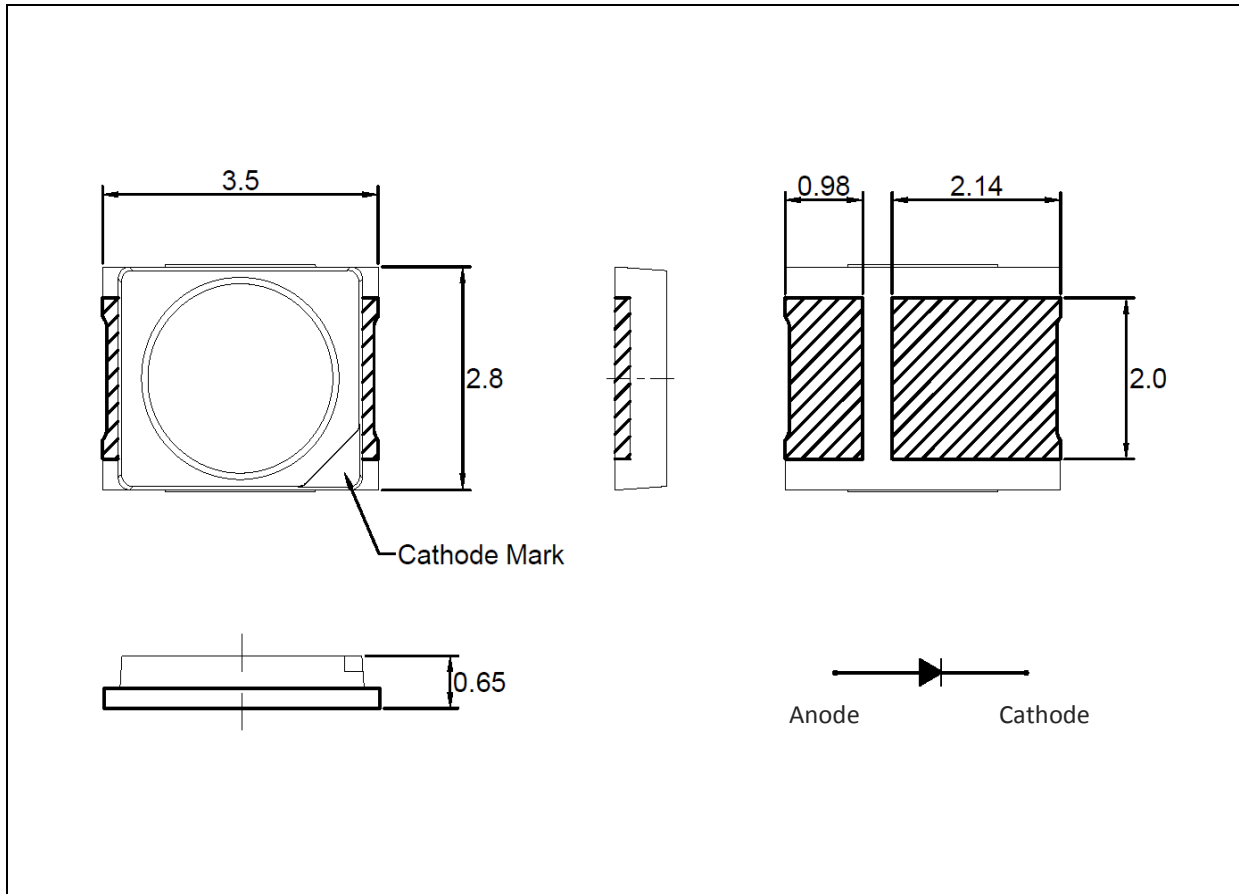
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	1.8	2.4	3.0	V	$I_F=350mA$
Luminous Flux	Φ_V	33	36	45	lm	$I_F=350mA$
Dominant Wavelength	λ_D	585	590	595	nm	$I_F=350mA$
Spectral Half Width	$\Delta\lambda$	---	20	---	nm	$I_F=350mA$
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	$I_F=350mA$

1. Luminous intensity (I_v) $\pm 15\%$, Forward Voltage (V_f) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$
2. IS standard testing

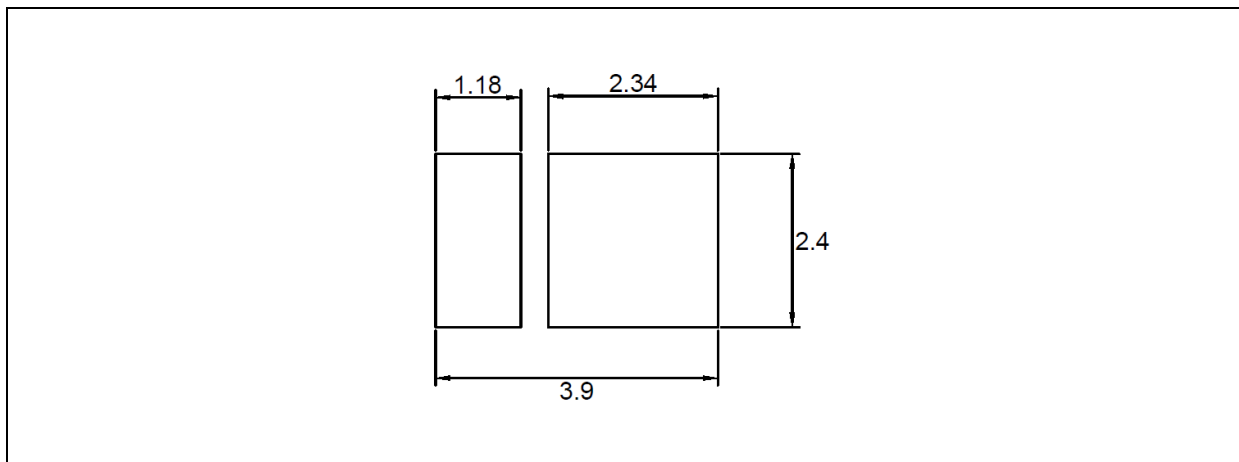
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 350\text{mA}$):

Code	Min.	Max.	Unit
D	1.8	1.9	V
E	1.9	2.0	
F	2.0	2.1	
G	2.1	2.2	
H	2.2	2.3	
I	2.3	2.4	
J	2.4	2.5	
K	2.5	2.6	
L	2.6	2.7	
M	2.7	2.8	
N	2.8	2.9	
O	2.9	3.0	

 Luminous Flux Classifications ($I_F = 350\text{mA}$):

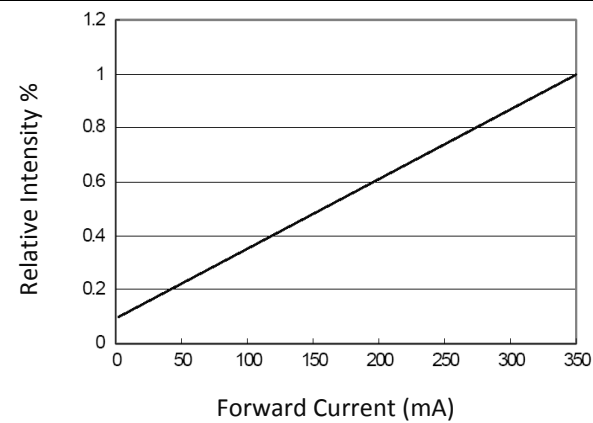
Code	Min.	Max.	Unit
F33T	33	36	lm
F36T	36	39	
F39T	39	42	
F42T	42	45	

 Dominant Wavelength Classifications ($I_F = 350\text{mA}$):

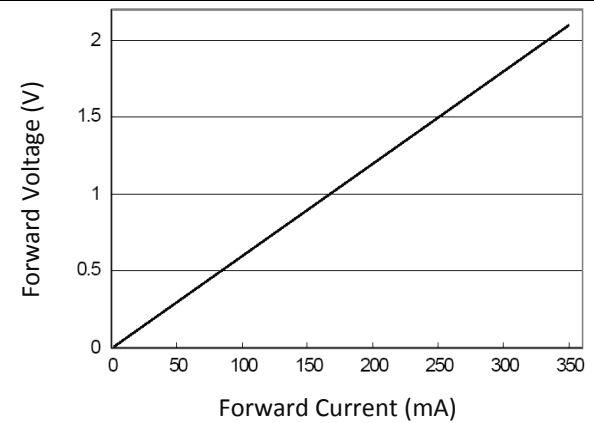
Code	Min.	Max.	Unit
15	585	587	nm
16	587	589	
17-1	589	590	
17-2	590	591	
17-3	591	592	
18	592	595	

ELECTRO-OPTICAL CHARACTERISTICS:

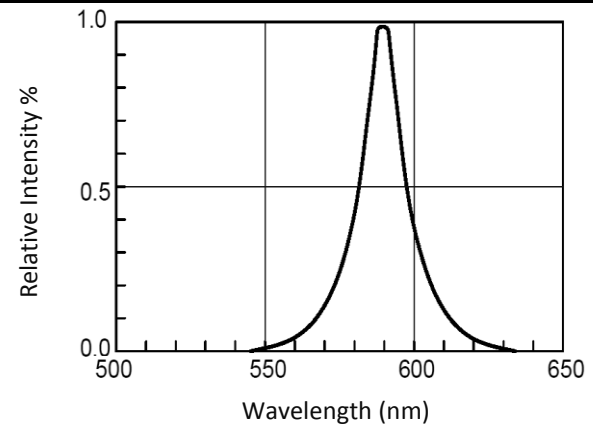
Relative Intensity v.s. Forward Current



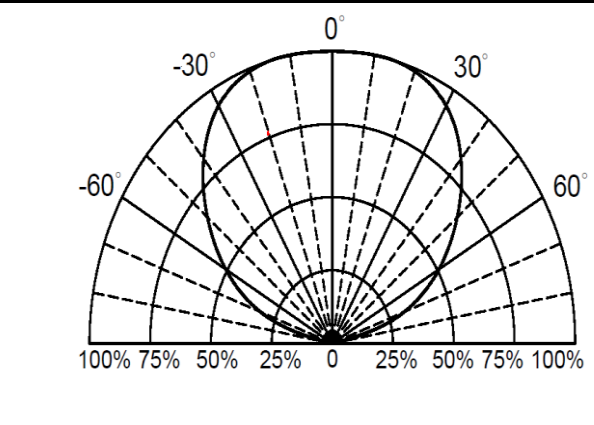
Forward Voltage v.s. Forward Current



Relative Intensity v.s. Wavelength

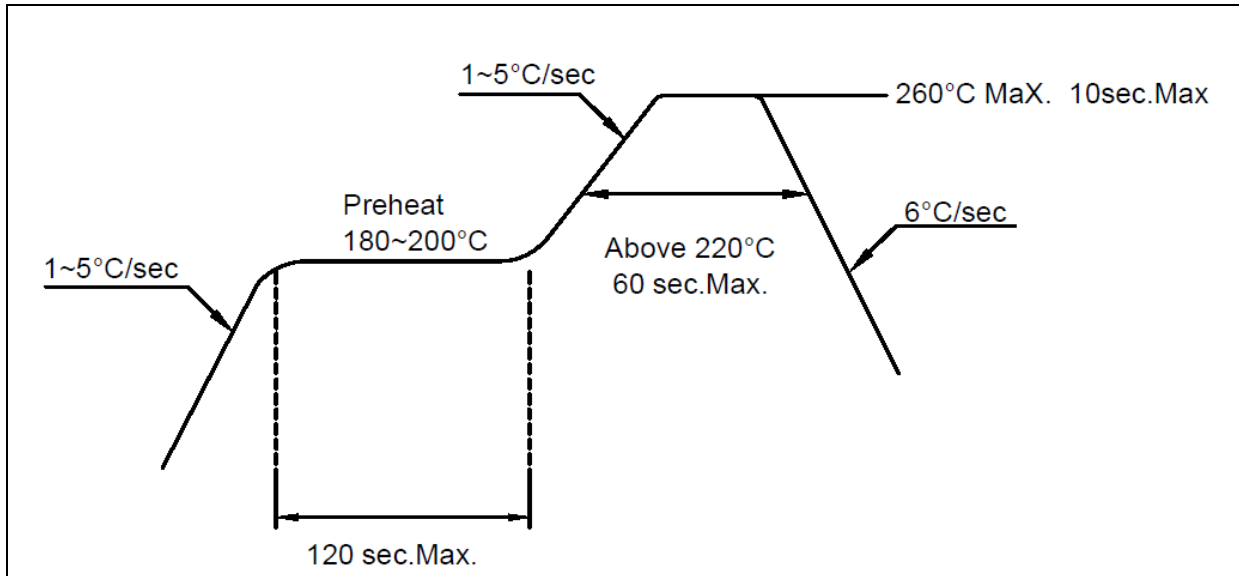


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:

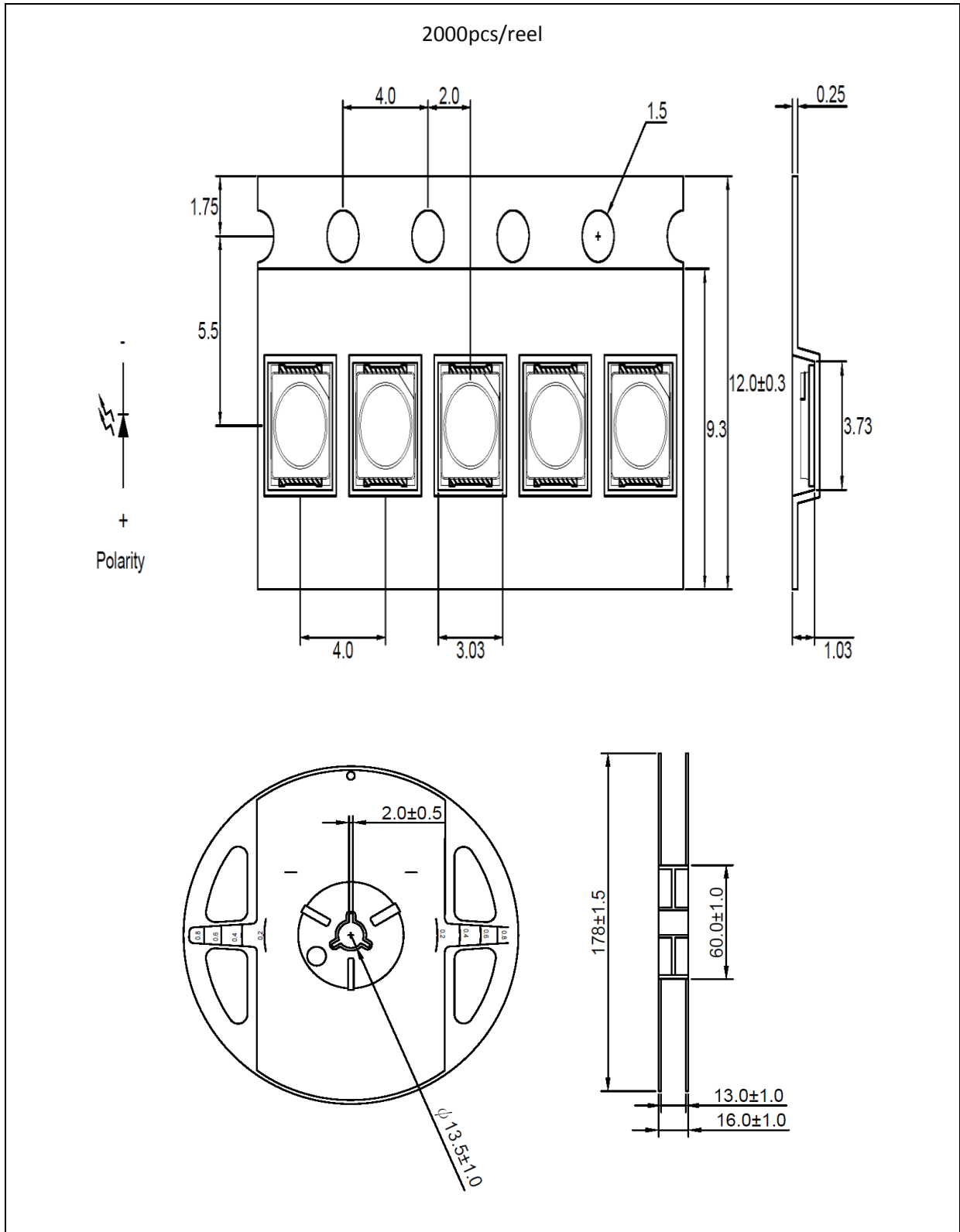


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.
3. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

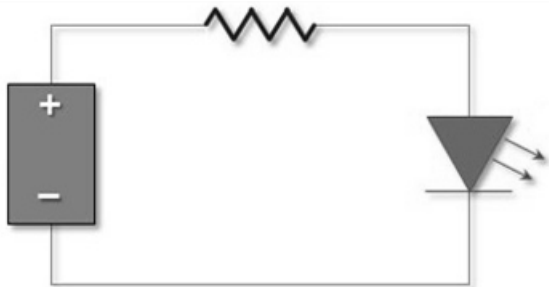
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	26/11/2014	Datasheet set-up.